# **Integrated Modules & Devices**

At the Integrated Modules & Devices segment demand for our communication devices is growing on the spread of smartphones and other mobile communications tools and faster data transmission speeds.

#### **Business Performance in the Year Ended March 2015**

Net sales at the segment increased 16.8% year on year to ¥49,510 million on higher sales of FBAR/SAW devices for mobile communications even as sales declined for power supply and high-frequency modules.

### **Key Initiatives in the Year Ended March 2015**

In devices for mobile communications, core components for smartphone, products with SAW and LTCC as their core technologies were developed. As a response to rapid growth in use of long-term evolution (LTE) protocols, the business developed and marketed applications for compact, low energy-consumption filter devices and front-end modules with matching circuits. Developing products using FBAR technologies was also a focus.

In mixed-function modules, it progressed with the construction of power supply modules and mixed-function modules meeting strong demand for modules that are energy saving, smaller, and thinner, introducing many differentiated products. In particular, EOMIN™, an in-house developed embedded-parts wiring board, contributed substantially to making smaller and thinner camera modules for smartphones.

In wireless communication modules, compact, low-profile modules for the growing near field wireless communication

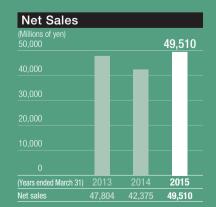
market along with various products, such as in-house developed modules with built-in antennas, meeting a wide range of needs were developed. Efforts were particularly focused on developing combination modules integrating Bluetooth®, wireless LAN, and other differing wireless communications standards into a unified module for rollout as products.

Moreover, to devise marketable solutions for new communication markets such as the digital consumer electronics and healthcare fields, modules with software support were developed and packaged into products.

#### **Future Initiatives**

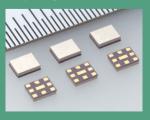
Among the initiatives we are moving forward with are a high-frequency module business centered on FBAR/SAW technologies, active rollout of super high-end products using EOMIN™, an embedded-parts wiring board born of the Group's original technology, and reinforcement of the power supply business with products for the energy market such as energy regeneration systems.

In FBAR/SAW devices for mobile communications, we are working to construct a production system that keeps pace with the rising built-in component count that has accompanied the spread of LTE, the main next-generation protocol.

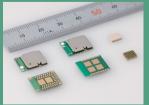


## Main Products

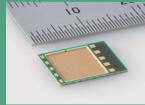
FBAR/SAW devices for mobile communications, power supply modules, high frequency modules and embedded-parts multilayer wiring <u>substrate EOMIN™</u>



FBAR/SAW devices for mobile communications



High frequency modules



Embedded-parts multilayer wiring substrate EOMIN™